

FEATURES

- | 35 Watts Peak Pulse Power per Line (tp=8/20μs)
- | Ultra low leakage: nA level
- | Working voltages : 24 V
- | Low leakage current
- | Low clamping voltage

APPLICATIONS

- | Smart phones
- | Display Ports
- | MDDI Ports
- | USB Ports
- | Digital Video Interface (DVI)
- | PCI Express and Serial SATA Ports



DFN1006

24L

Marking

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±15kV (air), ±15kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

- | | |
|-------------|------------------------------------|
| RoHS | Compliance with 2011/65/EU |
| HF | Compliance with IEC61249-2-21:2003 |



Schematic Symbol

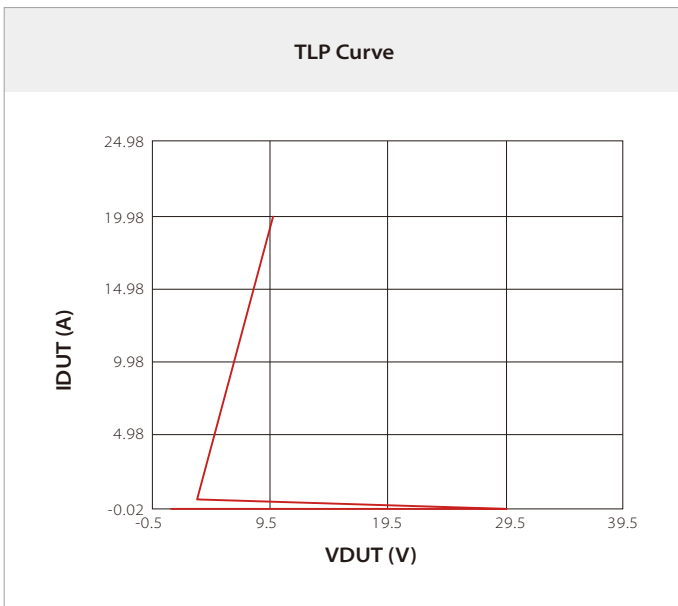
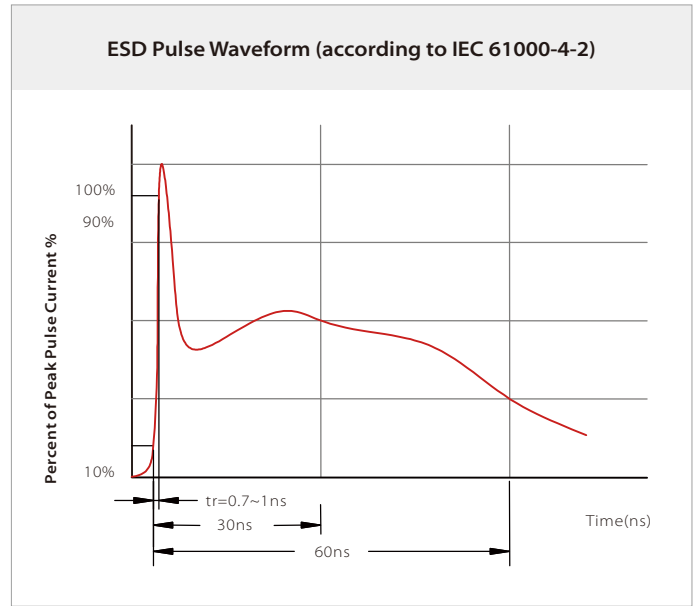
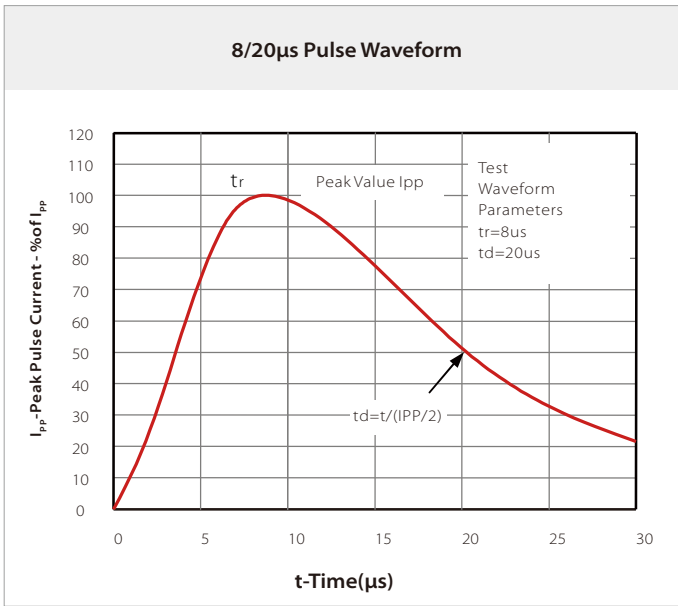
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{PP}	Peak Pulse Power (tp=8/20μs waveform)	35	Watts
T_J	Operating Temperature Range	-40 to +125	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C

ELECTRICAL CHARACTERISTICS

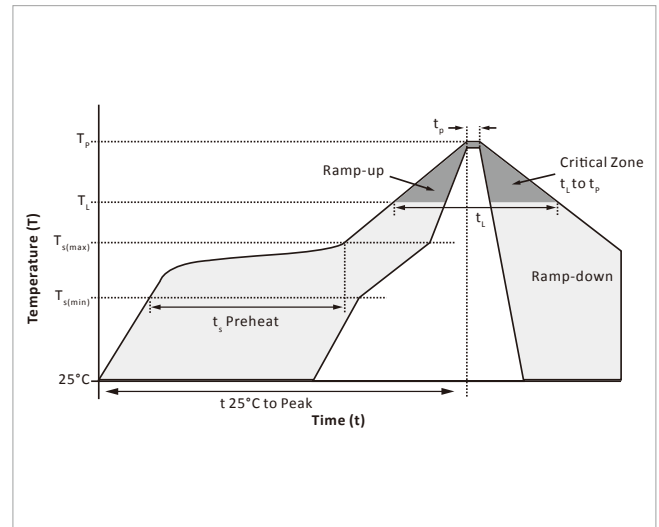
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	26.0	30.0		V
V_h	Holding Voltage	$I_T=100mA$	2.0	2.9		μA
I_R	Reverse Leakage Current	$V_{RWM}=24V$			0.2	μA
V_C	Clamping Voltage (Tp=8/20us)	$I_{pp}=1A, tp=8/20us$		4.0		V
V_C	Clamping Voltage (Tp=8/20us)	$I_{pp}=5A, tp=8/20us$		6.0	8.0	V
V_C	Clamping Voltage (Tp=8/20us)	TLP=16A(ESD=8KV)		8.2		V
I_{PP}	Peak Pulse Current (Tp=8/20us)	tp=8/20us			5	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$		0.5	0.7	pF

CHARACTERISTIC CURVES

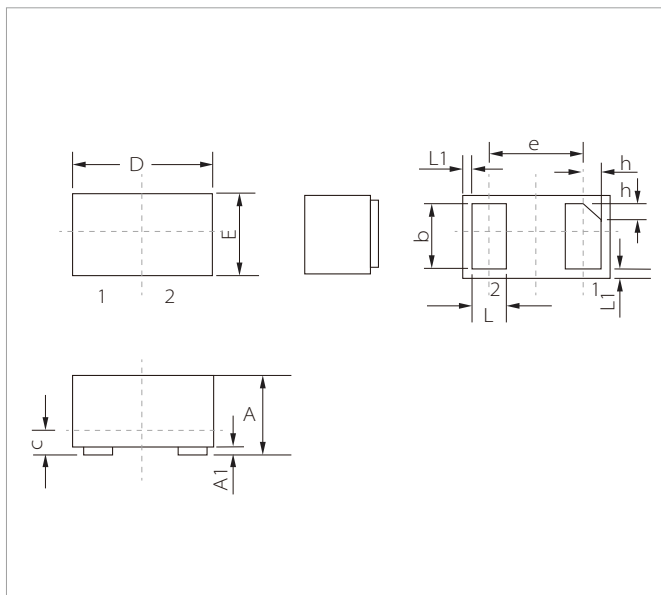


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
Reflow	$T_{s(max)}$ to T_L - Ramp-up Rate	3°C/second max
	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

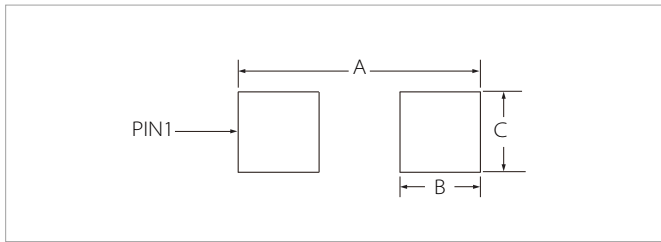


DFN1006 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.35	0.50	0.014	0.020
A1	0	0.05	0	0.002
b	0.40	0.55	0.016	0.022
c	0.12	0.18	0.005	0.007
D	0.95	1.05	0.037	0.041
e	0.65BSC		0.026BSC	
E	0.55	0.70	0.022	0.027
L	0.20	0.35	0.008	0.014
L1	0.05REF		0.002REF	
h	0.07	0.17	0.003	0.007

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
A	1.20	0.047
B	0.47	0.019
C	0.60	0.024

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE10F10B24MA-SP	DFN1006	10000PCS	7"

Headquarters

No.3387 Shendu Road Pujiang
I&E Park
Minhang Shanghai China
201000

Hotline

400-021-5756

Web

<https://www.semiware.com>

Sales Center

Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

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